Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	8 X 8 X 0.75 (6.4 EP)
Lead Count	56
Terminal Finish	100 Sn
MS Number	MS010617C

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.65E-02	86.20	862000	33.29	332870
Thermosets	Epoxy resin	Proprietary	3.93E-03	6.00	60000	2.32	23170
Thermosets	Phenol Resin	Proprietary	3.93E-03	6.00	60000	2.32	23170
Other inorganic materials	Metal Hydroxide	Proprietary	9.82E-04	1.50	15000	0.58	5792
Other inorganic materials	Carbon Black	1333-86-4	1.96E-04	0.30	3000	0.12	1158
Subtotal			6.55 E-02	100.00	1000000	38.62	386160

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	8.81 E-02	97.5	975000	51.93	519307
Copper & its alloys	Iron	7439-89-6	2.12 E-03	2.35	23500	1.25	12517
Copper & its alloys	Zinc	7440-66-6	1.08 E-04	0.12	1200	0.06	639
Copper & its alloys	Phosphorus	7723-14-0	2.71 E-05	0.03	300	0.02	160
Subtotal			9.03 E-02	100.00	1000000	53.26	532622

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.85 E-03	100.0	1000000	1.09	10933

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	3.90 E-04	100.0	1000000	0.23	2297

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	1.02 E-03	100.0	1000000	0.60	6012

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	9.02 E-03	100.0	1000000	5.32	53210

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.09 E-03	73.54	735400	0.64	6447
Other organic materials	Epoxy resin A	TS ref# 10013	1.09 E-04	7.35	73500	0.06	644
Others	Anhydride	TS ref# 10181	1.09 E-04	7.35	73500	0.06	644
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	4.37 E-05	2.94	29400	0.03	258
Other organic materials	Epoxy resin B	TS ref# 10237	4.37 E-05	2.94	29400	0.03	258
Others	Epoxy resin modifier	TS ref# 10038	4.37 E-05	2.94	29400	0.03	258
Others	Anhydride	TS ref# 10180	4.37 E-05	2.94	29400	0.03	258
Subtotal			1.49 E-03	100.0	1000000	0.88	8766

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.70 E-01**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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